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cont.

the invention is illustrated in Fig. 4 having the ground plug connected to the source terminal. The semiconductor device may of course be part of a semiconductor circuit, which may consist of a plurality of different semiconductor devices. A major advantage is that a more compact layout of the semiconductor circuit may be obtained, with a reduced number of contact pads.

In the Claims

Please **REPLACE** claims 4 and 5 and **ADD** claims 12 -16 as follows:

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4. (Amended) Semiconductor device according to claim 1, wherein said plug extends deeper into the initially doped substrate beyond PN-junctions.

5. (Amended) Semiconductor device according to claim 1, wherein the upper end of each plug is connected to said ground connection via an electrically conductive material.

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12. (New) Semiconductor device according to claim 5, wherein said material has a high conductivity.

13. (New) Semiconductor device according to claim 11, wherein said material is a metal material.

14. (New) Semiconductor device according to claim 1, wherein a plurality of plugs are provided for at least one ground connection to establish a high current electrical connection.

15. (New) Semiconductor device according to claim 1, wherein said device is a low voltage RF device.

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16. (New) Semiconductor device according to claim 1, wherein said plug is implemented outside an area limited by a trench, the device having the ground connection being arranged within the area.
